SN5402, SN54LS02, SN54S02, SN7402, SN74LS02, SN74S02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

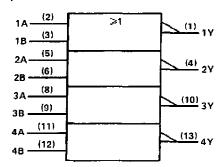
These devices contain four independent 2-input-NOR gates.

The SN5402, SN54LS02, and SN54S02 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7402, SN74LS02, and SN74S02 are characterized for operation from 0°C to 70°C .

FUNCTION TABLE (each gate)

	INP	UTS	OUTPUT
ı	A	В	Y
	Н	Х	L
	Х	Н	L
Ì	Ł	L] н

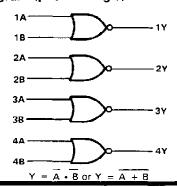
logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

logic diagram (positive logic)



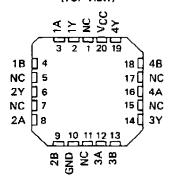
SN5402...J PACKAGE
SN54LS02, SN54S02...J OR W PACKAGE
SN7402...N PACKAGE
SN74LS02, SN74S02...D OR N PACKAGE
(TOP VIEW)

1Y	Цī	U14 VC0
1A	₫2	13∏ 4Y
18	□3	12 3 4 B
2Y	□4	11 4A
2A	□ 5	10 3 Y
2B	□ 6	9 <u></u> 3 B
GND	d7	g <u></u> 3A

SN5402 . . . W PACKAGE (TOP VIEW)

1A 🗀	ī	U	巾	4Y
18 [2	1:	3	4B
1Y 🗀	3	1;	冲	4A
V¢¢ □	4	• 1	巾	GND
2Y 🗀	5	1 (巾	3B
2A 🗀	6	9	ь	3A
2B 🗀	7	8	Þ	3Y

SN54LS02, SN54S02 . . . FK PACKAGE (TOP VIEW)

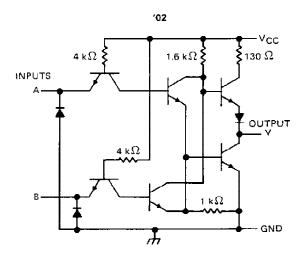


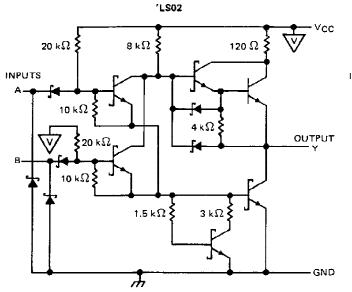
NC - No internal connection

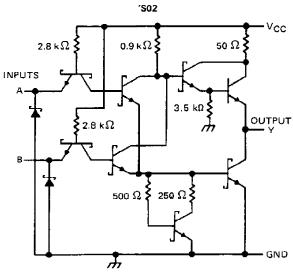
PRODUCTION DATA documents contain information current as of publication dats. Preducts conform to specifications per the terms of Tuxas Instruments standard warranty. Production processing does not necessarily include tasting of all parameters.



schematics (each gate)







Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
	5.5 V
'LS02	, , ,
Off-state output voltage	,
Operating free-air temperature range:	SN54'55°C to 125°C
	SN74'
Storage temperature range	, -65°C to 150°C

NOTE 1. Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5402			SN7402			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vac 5	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
V _{IH} I	High-level input voltage	2			2			٧	
VIL I	Low-level input voltage			8.0			0.8	٧	
Іон І	High-level output current			- 0.4			- 0.4	mΑ	
loL l	Low-level output current			16			16	mA	
T _A (Operating free-air temperature	55		125	٥		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TECT COMPLETIONS *			\$N5402			SN7402			
PARAMETER		TEST CONDITIONS †			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
Vικ	V _{CC} = MIN,	l = - 12 mA				- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{IL} = 0.8 V.	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		٧
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
Ц	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
11H	V _{CC} = MAX,	V1 = 2.4 V				40			40	μΑ
I _{IL}	V _{CC} = MAX,	V ₁ = 0.4 V				- 1.6			- 1.6	mΑ
¹ 0s§	V _{CC} = MAX			- 20		- 55	- 18		- 55	mΑ
^I ссн	V _{CC} = MAX,	V ₁ = 0 V	·	_	8	16		8	16	mΑ
CCL	V _{CC} = MAX,	See Note 2			14	27		14	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		TYP	MAX	UNIT
t _{PLH}					12	22	ns
^t PHL	A or B	Υ	$R_L = 400 \Omega$, $C_L = 15 pF$		8	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at VCC = 5 V, TA = 25°C.

[§] Not more than one output should be shorted at a time.

SN54LS02, SN74LS02 QUADRUPLE 2 INPUT POSITIVE NOR GATES

recommended operating conditions

	SN54LS02 SN74LS02	
	MIN NOM MAX MIN NOM MA	AX VNIT
V _{CC} Supply voltage	4.5 5 5.5 4.75 5 5.	.25 V
V _{IH} High-level input voltage	2 2	٧
VIL Low-level input voltage	0.7	0.8 V
OH High-level output current	- 0.4	0.4 mA
IOL Low-level output current	4	8 mA
TA Operating free-air temperature	- 55 125 0	70 °C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS T			SN54LS	502		SN74LE	02	l	
PARAMÉTER		TEST CONDITIONS (MIN	TYP‡	MAX	MIN	TYP\$	MAX	UNIT
٧ıĸ	VCC = MIN,	I ₁ = 18 mA				– 1.5			– 1.5	V
∨он	V _{CC} = MIN,	VIL = MAX,	¹ OH = - 0.4 mA	2.5	3.4		2.7	3.4		٧
V _{OL}	V _{CC} - MIN,	V _{1H} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	VCC = MIN,	V _{IH} = 2 V,	IOL = 8 mA					0.35	0.5] *
t _i	V _{CC} = MAX,	V _I = 7 V	· ·			0.1			0 .1	mΑ
Чн	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
HL	V _{CC} = MAX,	V) = 0.4 V				- 0.4			- 0.4	mΑ
los§	V _{CC} - MAX			- 20		- 100	- 20		- 100	mΔ
Іссн	V _{CC} = MAX,	V _I = 0 V			1.6	3.2		1.6	3.2	mА
ICCL	VCC = MAX,	See Note 2			2.8	5.4		2.8	5.4	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	MAX	UNIT	
₹PLH	A or R	V	D. = 2 kG	C 15 pc	10	15	nş
ФНL	A or B	'	RL = 2 kΩ,	C _L = 15 pF	10	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: One input at 4.5 V, all others at GND.

recommended operating conditions

			SN54S02			SN74S02		
		MIN	MIN NOM MAX MIN NOM MAX	UNIT				
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2		-	2			٧
۷ĮĻ	Low-level input voltage			8.0			0.8	V
lон	High-level output current			- 1			– 1	mΑ
loL	Low-level output current			20			20	mΑ
Тд	Operating free-air temperature	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS T			SN54S02			SN74S02			
PARAMETER			MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} - MIN,	I _I = -18 mA				-1.2			-1,2	٧
Voн	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		٧
VOL	VCC = MIN,	V _{IH} = 2 V.	IOL = 20 mA			0.5			0.5	V
l _I	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V ₁ = 2.7 V				50			50	μА
Iμ	V _{CC} = MAX,	V = 0.5 V				-2			-2	mA
l _{OS} §	V _{CC} = MAX			-40		-100	-40		-100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			17	29		17	29	mΑ
lccr	V _{CC} = MAX,	See Note 2	· · · · · · · · · · · · · · · · · · ·		26	45		26	45	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
tPLH			$R_1 = 280 \Omega$, $C_1 = 15 pF$	3.5	5,5	ns
tPHL	A or B	Y	R _L = 280 Ω, C _L = 15 pF	3.5	5,5	ns
tPLH			$R_1 = 280 \Omega$, $C_L = 50 pF$	5		ns
tPHL			$R_{\perp} = 280 \Omega$, $C_{\perp} = 50 pF$	5		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00401BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN5402J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN5402J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7402N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7402N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7402N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7402N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7402NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7402NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS02DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS02DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





om 17-Oct-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽
SN74LS02DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS02DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS02J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS02J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS02NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS02NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS02NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS02NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74S02DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S02DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SNJ5402J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5402J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5402W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5402W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS02FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC



PACKAGE OPTION ADDENDUM

17-Oct-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54LS02FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS02W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS02W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S02W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

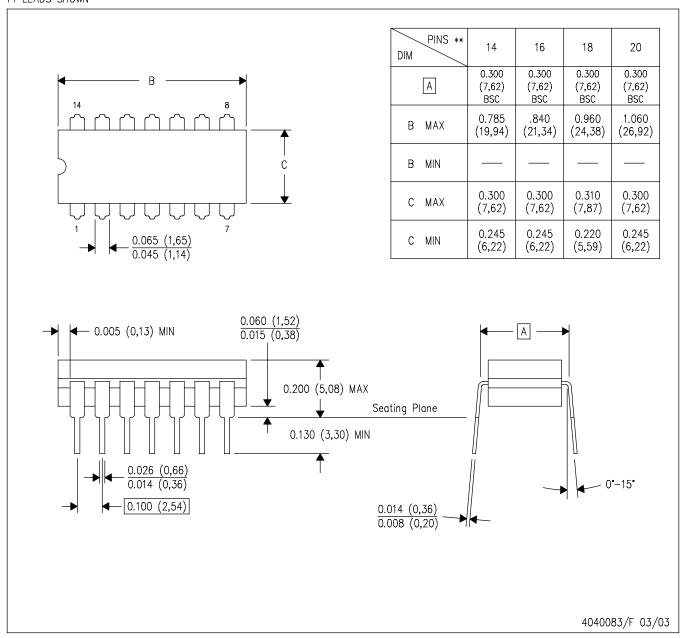
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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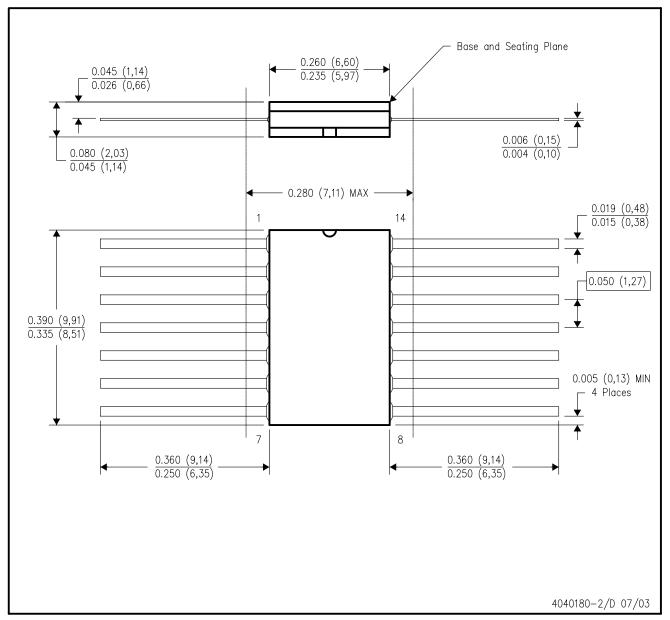
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



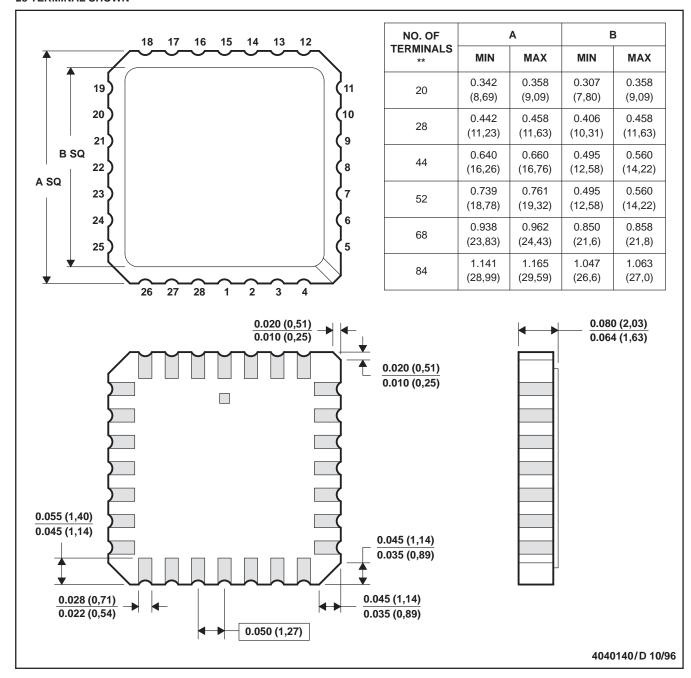
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

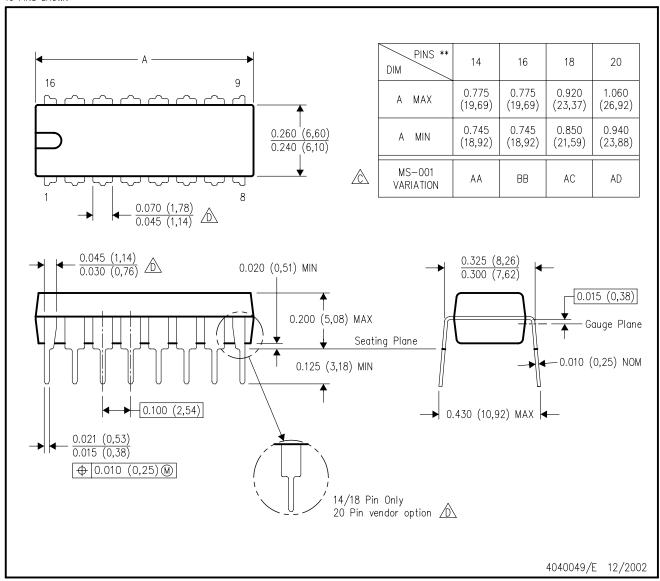
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

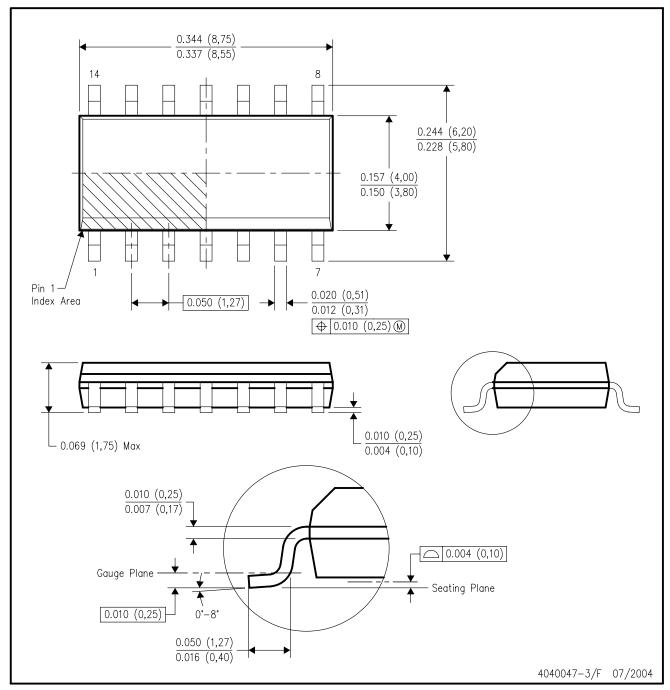


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

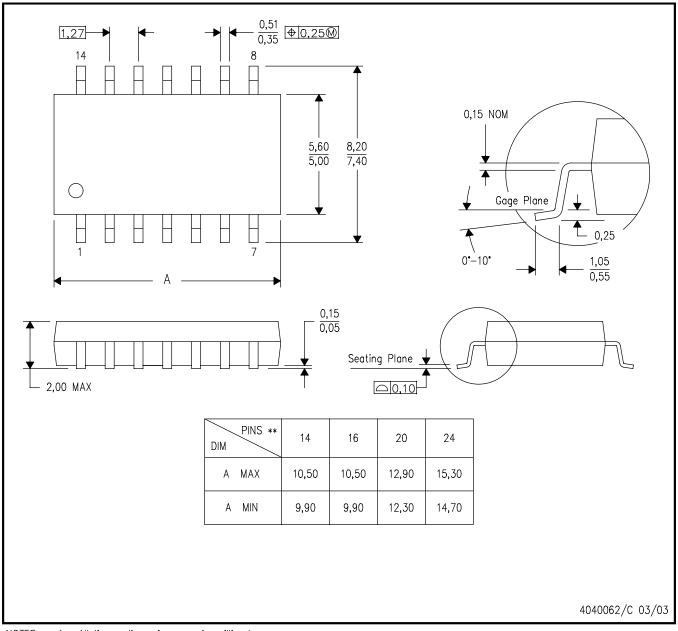


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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